

Amendment to the Specification:

(p. 19, last paragraph)

Referring again, in more detail to Fig. 1, a method and structure (in the fabrication of metal pad structures) is shown wherein a unique interlocking grid structure is formed. These interlocking structures form "islands" of interlocking "grid" structures (in three dimensions) to enhance adhesion among the various layer of the metal stack pad structure for improved wire bond strength. The method and structure of said interlocking grid structure 6 is formed by the patterning and etching of passivation material 4, e.g., insulating silicon oxide, silicon nitride, polyimide material, etc.. The said interlocking grid structure 6 is formed of patterned, passivating material 4 in a pad via contact region is , approximately 100 by 100 microns square and the size of the "island" structures are from about 10 to 25 microns in width, approximately 4 microns in height, and from about 4 to 10 in number per contact via pad structure. The said interlocking grid structure 6, formed in a pad via contact region forms in three dimensions, a "grid", group or an array of interlocking structures ("islands").